



## Material Content Data Sheet



<b>Sales Product Name</b>		BTS5012SDA		<b>Issued</b>		4. October 2018		
<b>MA#</b>		MA000913724						
<b>Package</b>		PG-TO252-5-11		<b>Weight*</b>		356.86 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	3.719	1.04	1.04	10421	10421
chip_2	inorganic material	silicon	7440-21-3	1.157	0.32	0.32	3243	3243
leadframe	inorganic material	phosphorus	7723-14-0	0.061	0.02		172	
	non noble metal	iron	7439-89-6	0.205	0.06		573	
	non noble metal	copper	7440-50-8	204.243	57.22	57.30	572334	573079
	non noble metal	aluminium	7429-90-5	1.170	0.33	0.33	3279	3279
wire	non noble metal	aluminium	7429-90-5	1.170	0.33	0.33	3279	3279
	organic material	carbon black	1333-86-4	1.380	0.39		3866	
encapsulation	plastics	epoxy resin	-	24.143	6.77		67653	
	inorganic material	silicondioxide	60676-86-0	112.436	31.51	38.67	315070	386589
leadfinish	non noble metal	tin	7440-31-5	5.072	1.42	1.42	14214	14214
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.076	0.02	0.02	214	215
solder	non noble metal	tin	7440-31-5	0.061	0.02		171	
	noble metal	silver	7440-22-4	0.076	0.02		214	
	non noble metal	lead	7439-92-1	2.917	0.82	0.86	8175	8560
	plastics	Polyimide	26023-21-2	0.143	0.04	0.04	400	400
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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